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#### OCTAL TRANSPARENT D-TYPE LATCH WITH 3-STATE OUTPUTS

### Description

The 74LVC373A provides eight transparent D-type latches. While the latch-enable (LE) input is high, the Q outputs follow the data (D) inputs. When LE is taken low, the Q outputs are latched at the logic levels set up at the D inputs. A buffered output-enable  $(\overline{\text{OE}})$  input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without interface or pullup components.  $\overline{\text{OE}}$  does not affect the internal operations of the latches. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

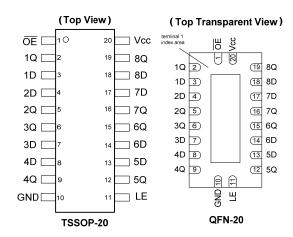
The device is designed for operation with a power supply range of 1.65V to 3.6V.

The inputs are tolerant to 5.5V allowing this device to be used in a mixed voltage environment. The device is fully specified for partial power down applications using  $I_{\text{OFF}}$ . The  $I_{\text{OFF}}$  circuitry disables the output preventing damaging current backflow when the device is powered down.

#### **Features**

- Supply Voltage Range from 1.65V to 3.6V
- Sinks or Sources 24mA at V<sub>CC</sub> = 3V
- CMOS Low Power Consumption
- I<sub>OFF</sub> Supports Partial Power Down Operation
- Inputs or Outputs Accept Up to 5.5V
- Inputs Can Be Driven by 3.3V or 5V Allowing for Mixed Voltage Applications
- Schmitt Trigger Action at All Inputs
- Typical V<sub>OLP</sub> (Quiet Output Ground Bounce) Less Than 0.8V with V<sub>CC</sub> = 3.3V and T<sub>A</sub> = +25°C
- Typical V<sub>OHV</sub> (Quiet Output dynamic VOH) Greater than 2.0V with V<sub>CC</sub> = 3.3V and T<sub>A</sub> = +25°C
- ESD Protection Tested per JESD 22
  - Exceeds 200-V Machine Model (A115)
  - Exceeds 2000-V Human Body Model (A114)
  - Exceeds 1000-V Charged Device Model (C101)
- Latch-Up Exceeds 250mA per JESD 78, Class II
- All devices are:
  - Totally Lead-Free & Fully RoHS compliant (Notes 1 & 2)
  - Halogen and Antimony Free. "Green" Device (Note 3)

### **Pin Assignments**



### **Applications**

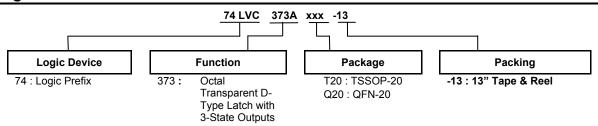
- General Purpose Logic
- Bus Driving
- Power Down Signal Isolation
- Wide array of products such as:
  - PCs, Notebooks, Netbooks, Ultrabooks
  - Networking Computer Peripherals, Hard Drives, CD/DVD ROM
  - TV, DVD, DVR, Set Top Box

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen and Antimony free, "Green" and Lead-Free.
- 3. Halogen and Antimony free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.



## **Ordering Information**



Part Number	Package	Package	Package	13" Tape	and Reel
Part Number	Code	(Note 4 & 5)	Size	Quantity	Part Number Suffix
74LVC373AT20-13	T20	TSSOP-20	6.4mm X 6.5mm X 1.2mm 0.65 mm lead pitch	2500/Tape & Reel	-13
74LVC373AQ20-13	Q20	V-QFN4525-20	2.5mm X 4.5mm X 0.95mm 0.50 mm lead pitch	2500/Tape & Reel	-13

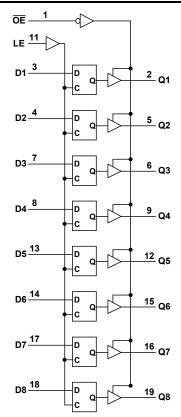
Notes:

- 4. Pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at http://www.diodes.com/datasheets/ap02001.pdf.
- 5. V-QFN4525-20 is a JEDEC recognized naming convention that specifies the package thickness category as V and the number 4525 describes the package as 4.5mm X 2.5mm.

## **Pin Descriptions**

= : • • · · · · · · · · · · · · ·						
Pin Number	Pin Name	Description				
1	ŌĒ	Output Enable				
2	Q1	Latch Output				
3	D1	Data Input				
4	D2	Data Input				
5	Q2	Latch Output				
6	Q3	Latch Output				
7	D3	Data Input				
8	D4	Data Input				
9	Q4	Latch Output				
10	GND	Ground				
11	LE	Latch Enable				
12	Q5	Latch Output				
13	D5	Data Input				
14	D6	Data Input				
15	Q6	Latch Output				
16	Q7	Latch Output				
17	D7	Data Input				
18	D8	Data Input				
19	Q8	Latch Output				
20	Vcc	Supply Voltage				

# **Logic Diagram**



## **Function Table**

(Each Latch)						
	INPUTS	OUTPUT				
ŌE	LE	D	Q			
L	Н	Н	Н			
L	Н	L	L			
Ш	L	Χ	$Q_0$			
Η	X	X	Z			



# Absolute Maximum Ratings (Notes 6 & 7)

Symbol	Description	Rating	Unit
ESD HBM	Human Body Model ESD Protection	2	kV
ESD CDM	Charged Device Model ESD Protection	1	kV
ESD MM	Machine Model ESD Protection	200	V
Vcc	Supply Voltage Range	-0.5 to +7.0	V
VI	Input Voltage Range	-0.5 to +7.0	V
I <sub>IK</sub>	Input Clamp Current V <sub>I</sub> < 0V	-20	mA
lok	Output Clamp Current V <sub>O</sub> < 0V	-50	mA
Io	Continuous Output Current -0.5V < V <sub>O</sub> V <sub>CC</sub> +0.5V	±50	mA
Icc	Continuous Current Through V <sub>CC</sub>	100	mA
I <sub>GND</sub>	Continuous Current Through GND	-100	mA
T <sub>J</sub>	Operating Junction Temperature	-40 to +150	°C
T <sub>STG</sub>	Storage Temperature	-65 to +150	°C
P <sub>TOT</sub>	Total Power Dissipation	500	mW

Notes:

- 6. Stresses beyond the absolute maximum may result in immediate failure or reduced reliability. These are stress values and device operation should be within recommend values.
- 7. Forcing the maximum allowed voltage could cause a condition exceeding the maximum current or conversely forcing the maximum current could cause a condition exceeding the maximum voltage. The ratings of both current and voltage must be maintained within the controlled range.

# **Recommended Operating Conditions** (Note 8)

Symbol	Parameter	Conditions	Min	Max	Unit
V	Cupply Voltage	Operating	1.65	3.6	V
$V_{CC}$	Supply Voltage	Data Retention Only	1.5	_	V
VI	Input Voltage	_	0	5.5	V
Vo	Output Voltage	_	0	V <sub>CC</sub>	V
	I <sub>OH</sub> High-Level Output Current	V <sub>CC</sub> = 1.65V	_	-4	
		V <sub>CC</sub> = 2.3V	_	-8	4
ЮН		V <sub>CC</sub> = 2.7V	— -12	-12	mA
		V <sub>CC</sub> = 3.0V	_	-24	1
		V <sub>CC</sub> = 1.65V	_	4	
	Land and Ortant Orman	V <sub>CC</sub> = 2.3V	_	8	
loL	Low-Level Output Current	V <sub>CC</sub> = 2.7V	_	12	mA mA
		V <sub>CC</sub> = 3.0V	_	24	1
Δt/ΔV	Input Transition Rise or Fall Rate		_	10	ns/V
T <sub>A</sub>	Operating Free-Air Temperature		-40	+125	°C

Note:

8. Unused inputs should be held at  $V_{\text{CC}}$  or ground.



# **Electrical Characteristics**

Comple ed	Parameter	Test Conditions	V	T <sub>A</sub> = -40°0	C to +85°C	T <sub>A</sub> = +85°C	to +125°C	Unit
Symbol	Parameter	lest Conditions	V <sub>CC</sub>	Min	Max	Min	Max	Unit
			1.65V to 1.95V	V <sub>CC</sub> X 0.65	_	V <sub>CC</sub> X 0.65	_	
$V_{IH}$	High-Level Input Voltage		2.3V to 2.7V	1.7	_	1.7	_	V
	Voltage		3.0V to 3.6V	2	_	2	_	
	Lave Lavel Immed		1.65V to 1.95V	_	V <sub>CC</sub> X 0.35	_	V <sub>CC</sub> X 0.35	
$V_{IL}$	Low-Level Input Voltage		2.3V to 2.7V	_	0.7	_	0.7	V
	Tonago		3.0V to 3.6V	_	0.8	_	8.0	
		$I_{OH} = -50 \mu A$	1.65V to 3.6V	V <sub>CC</sub> -0.2	_	V <sub>CC</sub> -0.3	_	
		$I_{OH} = -4mA$	1.65V	1.2	_	1.05	_	
V	High-Level Output	I <sub>OH</sub> = -8mA	2.3V	1.7	_	1.65	_	
$V_{OH}$	Voltage	1 40 4	2.7V	2.2	_	2.05	_	V
		$I_{OH} = -12mA$	3.0V	2.4	_	2.48	_	V
		$I_{OH} = -24 \text{mA}$	3.0V	2.3	_	2.0	_	
		I <sub>OL</sub> = 100μA	1.65V to 3.6V	_	0.2	_	0.3	
		I <sub>OL</sub> = 4mA	1.65V	_	0.45	_	0.65	
$V_{OL}$	Low-Level Output Voltage	I <sub>OL</sub> = 8mA	2.3V	_	0.60	_	0.80	V
	Voltage	I <sub>OL</sub> = 12mA	2.7V	_	0.40	_	0.60	
		I <sub>OL</sub> = 24mA	3.0V	_	0.55	_	0.80	
I <sub>OFF</sub>	Power Down Leakage Current	$V_I$ or $V_O = 0$ or 5.5V	0V	_	±10	_	20	μΑ
l <sub>l</sub>	Input Current Control Pins	V <sub>I</sub> = GND or 5.5V	0 to 3.6V	_	±5	_	±20	μΑ
l <sub>OZ</sub>	Z-state Current Including Input Current I/O Pins	V <sub>I</sub> = GND or 5.5V V <sub>O</sub> = 0 to 5.5V	3.6V	_	±5	_	±20	μΑ
Icc	Supply Current	$V_I = GND \text{ or } V_{CC}, I_O = 0$	3.6V	_	10	_	40	μA
Δlcc	Additional Supply Current	One input at Vcc-0.6V lo = 0A	2.7V to 3.6V	_	500	_	5000	μΑ
C	Innut Canacitance	Control Pins $V_1 = GND$ or	0V to 3.6V	4.0 ty	ypical	4.0 ty	/pical	nE
C <sub>i</sub>	Input Capacitance	I/O Pins V <sub>CC</sub>	0 0 10 3.00	5.5 ty	ypical	5.5 ty	/pical	pF



# **Switching Characteristics**

Comple of	Damamatan	Test	.,		T <sub>A</sub> = +25°C			+85°C	+85°C to	+125°C	l lmi4	
Symbol	Parameter	Conditions	V <sub>cc</sub>	Min	Тур.	Max	Min	Max	Min	Max	Unit	
			1.8V ± 0.15V	5.0	2.5		5.0		5.5			
	Pulse Width	Figure 1	2.5V ± 0.3V	4.0	2.0		4.0		4.5		20	
t <sub>W</sub>	LE	Figure 1	2.7V	3.0	1.7		3.0		3.5		ns	
			$3.3V \pm 0.3$	3.0	1.5		3.0		3.5			
			1.8V ± 0.15V	4.0	2.0		4.0		4.5			
t <sub>su</sub>	Set-up Time D <sub>N</sub> to	Figure 1	2.5V ± 0.3V	3.0	1.5		3.0		3.5		ns	
LSU	LE	r igure i	2.7V	2.0	1.0		2.0		2.5		115	
			$3.3V \pm 0.3$	2.0	1.0		2.0		2.5			
			1.8V ± 0.15V	3.0	1.5		3.0		3.5			
t <sub>H</sub>	Hold Time	Figure 1	2.5V ± 0.3V	2.0	1.0		2.0		2.5		ns	
Ч	D <sub>N</sub> to LE	Figure 1	2.7V	1.5	1.0		1.5		2.0		115	
			$3.3V \pm 0.3$	1.5	1.0		1.5		2.0			
	$\begin{array}{ccc} & & & Propagation \ Delay \\ t_{PD} & & D_N \ to \ Q_N \end{array} \qquad \begin{array}{c} Figure \ 1 \end{array}$		1.8V ± 0.15V	1	6	12.2	1	12.7	1	16.9		
+		Figure 1	2.5V ± 0.3V	1	3.9	7.8	1	8.3	1	8.7	ns	
чPD		i igule i	2.7V	1	4.2	7.8	1	7.3	1	9.5	-	
			$3.3V \pm 0.3$	1.5	3.8	6.8	1.5	6.3	1.5	8.0		
			1.8V ± 0.15V	1	7	14.8	1	15.3	1	22.5		
t <sub>PD</sub>	Propagation Delay	Figure 1	Figure 1	2.5V ± 0.3V	1	4.5	10	1	10.5	1	12.4	ns
<b>L</b> PD	LE to Q <sub>N</sub>			i iguic i	2.7V	1	5.4	8.2	1	9.5	1	12.0
			$3.3V \pm 0.3$	1.5	4.4	7.2	1.5	8.5	1.5	11.0		
			1.8V ± 0.15V	1	7.8	16.5	1	17	1	14.2		
t <sub>EN</sub>	Enable Time	Figure 1	2.5V ± 0.3V	1	4	9	1	9.5	1	8.2	ns	
LEN	$\overline{OE}$ to $Q_N$	i iguie i	2.7V	1	4.4	8.3	1	8.5	1	10.0	113	
			$3.3V \pm 0.3$	1.7	4.1	7.3	1.7	7.5	1.7	9.0		
			1.8V ± 0.15V	1	7.8	16.5	1	17	1	14.2		
t <sub>DIS</sub>	Disable Time  OE to Q <sub>N</sub>	Figure 1	$2.5V \pm 0.3V$	1	4	9	1	9.5	1	8.2	ns	
UIS		i iguic i	2.7V	1	4.4	8.3	1	8.5	1	10.0	113	
			$3.3V \pm 0.3$	1.7	4.1	7.3	1.7	7.5	1.7	9.0		
	- · · · -		1.8V ± 0.15V	1	7.8	16.5	1	17	1	14.2		
t <sub>DIS</sub>	Disable Time	Figure 1	2.5V ± 0.3V	1	4	9	1	9.5	1	8.2	ns	
บเธ	$\overline{OE}$ to $Q_N$	i iguio i	2.7V	1	4.4	8.3	1	8.5	1	10.0		
			$3.3V \pm 0.3V$	1.7	4.1	7.3	1.7	7.5	1.7	9.0		
tsk(0)	Output Skew Time		$3.3V \pm 0.3V$			1.0				1.5	ns	

# **Operating Characteristics**

 $T_A = +25^{\circ}C$ 

Symbol	Parameter	Test Conditions	Vcc	Тур	Unit
	Dower dissination	F = 10MHz	1.8V ± 0.15V	9.9	
$C_{pd}$	Power dissipation capacitance per gate	Outputs Enabled -	2.5V ± 0.3V	10.2	pF
	oapaoitarioe per gate		$3.3V \pm 0.3V$	10.6	

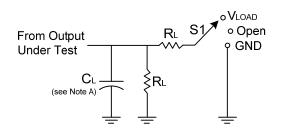
# **Package Characteristics**

Symbol	Parameter	Package	Test Conditions	Min	Тур	Max	Unit
$\theta_{JA}$	Thermal Resistance Junction-to-Ambient	TSSOP-20	(Note 9)	_	74	_	°C/W
θ <sub>JC</sub>	Thermal Resistance Junction-to-Case	TSSOP-20	(Note 9)	_	15	_	°C/W
$\theta_{JA}$	Thermal Resistance Junction-to-Ambient	V-QFN4525-20	(Note 9)	_	67	_	°C/W
θ <sub>JC</sub>	Thermal Resistance Junction-to-Case	V-QFN4525-20	(Note 9)	_	20	_	°C/W

Note: 9. Test conditions for TSSOP-20 and V-QFN4525-20: Devices mounted on 4 layer FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout per JESD 51-7.

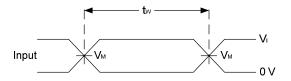


### **Parameter Measurement Information**

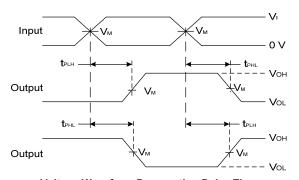


TEST	<b>S</b> 1
t <sub>PLH</sub> /t <sub>PHL</sub>	Open
$t_{PLZ}/t_{PZL}$	Vload
t <sub>PHZ</sub> /t <sub>PZH</sub>	GND

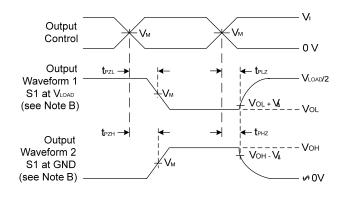
.,	In	puts	.,	, ,				
V <sub>cc</sub>	$V_{l}$	t <sub>r</sub> /t <sub>f</sub>	V <sub>M</sub>	$V_{LOAD}$	C∟	$R_{L}$	<b>V</b> Δ	
1.8V±0.15V	V <sub>CC</sub>	≤2ns	V <sub>CC</sub> /2	2 x V <sub>CC</sub>	30pF	1ΚΩ	0.15V	
2.5V±0.2V	$V_{CC}$	≤2ns	V <sub>cc</sub> /2	2 x V <sub>CC</sub>	30pF	500Ω	0.15V	
2.7V	2.7V	≤2.5ns	1.5V	6V	50pF	500Ω	0.3V	
3.3V±0.3V	2.7V	≤2.5ns	1.5V	6V	50pF	500Ω	0.3V	



#### **Voltage Waveform Pulse Duration**



**Voltage Waveform Propagation Delay Times Inverting and Non Inverting Outputs** 



**Voltage Waveform Enable and Disable Times** Low and High Level Enabling

- A. Includes test lead and test apparatus capacitance. Notes:
  - B. All pulses are supplied at pulse repetition rate ≤ 10 MHz.
  - C. Inputs are measured separately one transition per measurement.
  - D.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis.}$

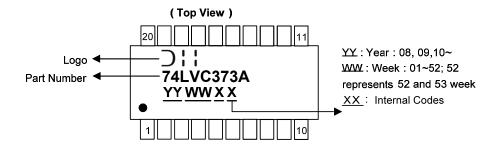
  - E.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{EN0}$  F.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{PD.}$

Figure 1 Load Circuit and Voltage Waveforms



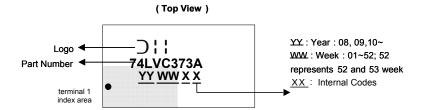
## **Marking Information**

#### (1) TSSOP20



Part Number	Package
74LVC373AT20	TSSOP-20

### (2) QFN-20 (V-QFN4525-20)



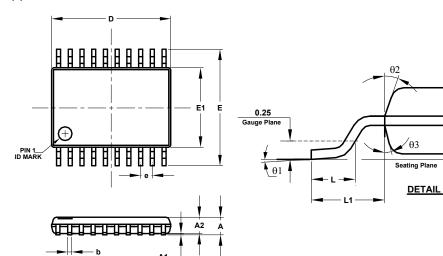
Part Number	Package
74LVC373AQ20	V-QFN4525-20



# Package Outline Dimensions (All Dimensions in mm)

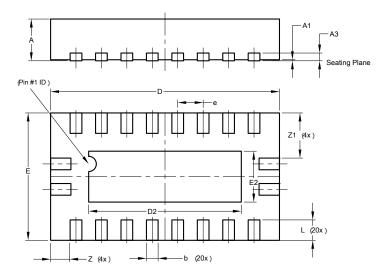
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.

#### (1) TSSOP-20



TSSOP-20				
Dim	Min	Max	Тур	
Α	-	1.20	-	
A1	0.05	0.15	-	
A2	0.80	1.05	-	
b	0.19	0.30	-	
С	0.09	0.20	-	
D	6.40	6.60	6.50	
Е	6.20	6.60	6.40	
E1	4.30	4.50	4.40	
е	0.65 BSC			
L	0.45	0.75	0.60	
L1	1.0 REF			
θ1	0°	8°	-	
θ2	10°	14°	12°	
θ3	10°	14°	12°	
All Dimensions in mm				

#### (2) QFN-20 (V-QFN4525-20)



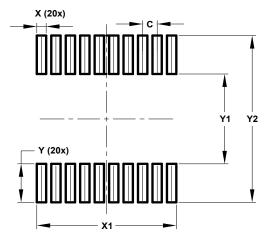
V-QFN4525-20				
Dim	Min	Max	Тур	
Α	0.75	0.85	0.80	
A1	0.00	0.05	0.02	
A3	-	-	0.15	
b	0.18	0.30	0.23	
D	4.45	4.55	4.50	
D2	2.85	3.15	3.00	
Е	2.45	2.55	2.50	
E2	0.85	1.15	1.00	
е	0.50BSC			
L	0.30	0.50	0.40	
Z	-	-	0.385	
Z1	-	-	0.885	
All Dimensions in mm				



# **Suggested Pad Layout**

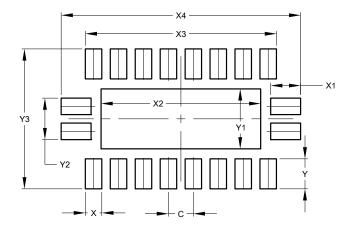
Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.

### (1) TSSOP-20



Dimensions	Value (in mm)
С	0.650
Х	0.420
X1	6.270
Υ	1.789
Y1	4.160
Y2	7.720

### (2) QFN-20 (V-QFN4525-20)



Dimensions	Value (in mm)
С	0.500
Х	0.330
X1	0.600
X2	3.200
Х3	3.830
X4	4.800
Υ	0.600
Y1	1.200
Y2	0.830
Y3	2.800



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